



Podium discussion moderator:

**Prof. Dr.-Ing. habil. Dr. H. C. Mult. Klaus-Jürgen
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Panel Discussion:

Trends in automotive electronics

Prof. **Klaus Wolter's** research interests have embraced many aspects of microelectronics packaging, including substrate technologies, assembly technologies, photonic packaging, MEMS, joining technologies, reliability of electronic packages, and non-destructive test methods.

He is well known as the co-editor and co-author of six textbooks, co-editor of three book series with a total of 39 books, author and co-author of more than 200 papers.

He is a senior member of IEEE-CPMT.

Prof. Wolter was the Director of the Electronic Packaging Lab at TU Dresden from 2003 to 2014. From March 2015 to March 2017, he was a visiting professor at the 3D Systems Packaging Research Center of Georgia Tech Atlanta where he researched on system-integration for advanced automotive electronics. Currently he is a senior professor at TU Dresden.